

Product Name:	HPL - 599 MicrospaceXS	
	MicrospaceXS	
Product Manager:	Dorian MOYNE	
Subject:	Notification of Planned Change	
Distribution:	Affected customers	
Type of Change:	Design Change	
Change Description:	Plating specification change and drawing update. No impact on product specification or performance.	
Reason for Change:	For internal process improvement, and crimping process improvement. To lower the risk of having parts stuck in the crimping die during the wire crimping process.	
Affected Parts:	10155447 / 10155449	
Effective Date of Change:	April,01 2024	
Last Time Buy Date:	NA	
Earliest Disty Return Date:	NA	
Last Time Shipment Date:	NA	
Datasheet Attached?	Yes	
Qual/Test Data Attached?	Yes	
Samples Availability Date:	01 January ,2024	
Available Alternatives?		
Questions?	<i>Contact your local ACS Representative, or Product Manager</i>	
	<i>Dorian MOYNE / Product Manager</i>	
	<i>dorian.moyne@amphenol-fci.com</i>	

Note:

Customers should contact Product Line Manager (or their local Amphenol Representative) directly regarding any concern on the PCN. Lack of any such customer feedback within three weeks of PCN release date will be interpreted as non-objection .